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- **32**. The system of claim **27**, wherein the collected characteristics further comprise process characteristics associated with the first fabrication process.
- 33. The system of claim 27, wherein collected characteristics further comprise metrology characteristics of the semiconductor device.
- **34**. The system of claim **27**, wherein collected characteristics further comprise control characteristics.
 - 35. A system, comprising:
 - means for providing a set of initial characteristic values associated with the semiconductor device;
 - means for performing a first fabrication process on the semiconductor device;
 - means for collecting fabrication data associated with the first fabrication process;
 - means for replacing at least one of the initial characteristic values with the fabrication data collected for the first fabrication process to generate a first modified set of characteristic values; and

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means for predicting a first value for at least one electrical characteristic of the semiconductor device based on the first modified set of characteristic values.

36. A system, comprising:

- means for storing characteristics associated with the processing of a semiconductor device collected during its fabrication:
- means for providing a vector of initial characteristic values associated with the semiconductor device;
- means for updating the vector with the collected characteristics; and
- means for modeling at least one electrical characteristic of the semiconductor device based on the updated vector.

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